

Job Opening at TSMC Design Solution, Corporate Research (CR)

Basic Information	
Title/Function	Circuit Design Engineer
Reporting to:	Meng-Fan (Marvin) Chang, Design Solution, Corporate Research (CR)
Location:	Taiwan Head Quarter or US (San Jose, CA) with 3+months at HQ per year
Roles and Responsibilities	
Role:	<ol style="list-style-type: none"> 1. Research on circuit designs for future 3D-IC, high-density memory, computing-in-memory for AI, digital AI chips, Cold-CMOS chips, and security-aware chips 2. Interaction with University PIs (US, EU, and Asia) and SRC for TSMC-University collaboration.
Key Areas of Responsibility	Conduct research in the field of circuit designs for future high-density memory and computing-in-memory for AI applications in collaboration with different departments at TSMC as well as the academia
Requirements	
Qualifications: (Education, Skills, Certificates, etc.)	<ul style="list-style-type: none"> • Ph.D. in Computer Science and Electrical Engineering or related field • Hands-on experience on circuit designs for memory, analog or digital blocks • Having knowledge of digital designs is a plus • Having knowledge of AI hardware is a plus • Having knowledge of security hardware is a plus • Having knowledge of 3D-IC architecture is a plus • Strong technical problem-solving and analytical skills • Familiar with design tools (schematic composer, spice simulation, digital design flow, etc.) • Having publications at top conferences or journals is a plus • Good written and communication skills in English
Languages:	English and/or Chinese (optional)
Key Experience:	Tapeout experience for memory, digital or analog circuits
Personal Attributes:	<ul style="list-style-type: none"> • Self-driven and pro-active • Good teamwork skills

Contact Person: Meng-Fan (Marvin) Chang, mfchang@tsmc.com